10.2 inch
E-paper Display Series
GDEM102T91

GooDisplay ®

Product Specifications

Customer	Standard
Description	10.2" E-PAPER DISPLAY
Model Name	GDEM102T91
Date	2023/07/14
Revision	1.0

	Design Engineering		
	Approval	Check	Design
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1. Over View

GDEM102T91 is an Active Matrix Electrophoretic Display (AM EPD), with interface and a reference system design. The display is capable to display image at 1-bit white and black full display capabilities. The 10.2inch active area contains 960×640 pixels. The module is a TFT-array driving electrophoresis display, with integrated circuits including gate driver, source driver, MCU interface, timing controller, oscillator, DC-DC, SRAM, LUT, VCOM. Module can be used in portable electronic devices, such as Electronic Shelf Label (ESL) System.

2. Features

◆960×640 pixels display

◆High contrast High reflectance

◆Ultra wide viewing angle Ultra low power consumption

◆Pure reflective mode

◆Bi-stable display

◆Commercial temperature range

◆Landscape portrait modes

◆Hard-coat antiglare display surface

◆Ultra Low current deep sleep mode

◆On chip display RAM

◆Waveform can stored in On-chip OTP or written by MCU

◆Serial peripheral interface available

◆On-chip oscillator

◆On-chip booster and regulator control for generating VCOM, Gate and
  Source driving voltage

◆I^2C signal master interface to read external temperature sensor
◆Built-in temperature sensor

3. Mechanical Specification

Parameter	Specifications	Unit	Remark
Screen Size	10.2	Inch	
Display Resolution	960(H)×640(V)	Pixel	DPI:113
Active Area	215.52×143.68	mm	
Pixel Pitch	0.2245×0.2245	mm	
Pixel Configuration	Rectangle		
Outline Dimension	224(H)×157 (V) ×1.0(D)	mm	
Weight	62.2±0.5	g	

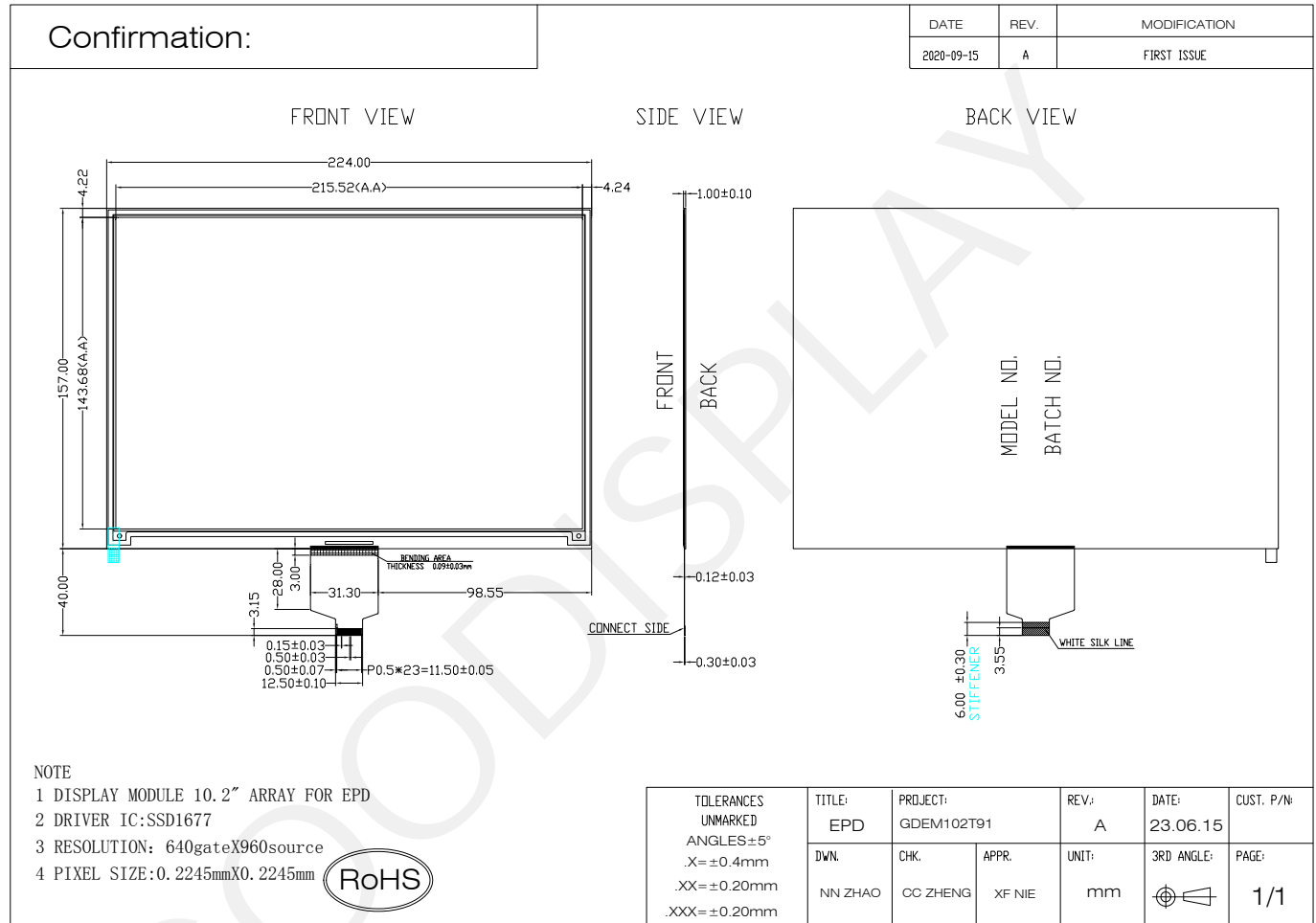| Symbol	Parameter	Conditions	Min	Typ.	Max	Units	Notes
KS	Black State L* value		-	18	20		3-1
	Black Ghosting △L		-	1	-		3-1
WS	White State L* value		66	67	-		3-1
	White Ghosting △L		-	1	-		3-1
R	White　Reflectivity	White	30	34	-	%	3-1
CR	Contrast Ratio	Indoor	15:1	20:1	-		3-1 3-2
GN	2Grey Level	-	-	-	-		
Life		Temp:23±3°C Humidity:55±10%RH		5years			3-3

Notes: 3-1. Luminance meter: Eye-One Pro Spectrophotometer.

3-2. CR=Surface Reflectance with all white pixel/Surface Reflectance with all black pixels.

3-3. When the product is stored. The display screen should be kept white and face up.

L: black and white luminance value, A: red luminance value,   E: color difference

4.Mechanical Drawing of EPD Module

DATE	REV.	MODIFICATION
2020-09-15	A	FIRST ISSUE

Confirmation:

FRONT VIEW

SIDE VIEW

BACK VIEW

224.00

215.52(A.A)

4.22

4.24

1.00±0.10

157.00

143.68(A.A)

FRONT

BACK

MODEL NO.

BATCH NO.

BENDING AREA
THICKNESS 0.09±0.03mm

28.00

3.00

31.30

98.55

0.12±0.03

40.00

3.15

CONNECT SIDE

0.30±0.03

0.15±0.03
0.50±0.03
0.50±0.07
12.50±0.10

P0.5*23=11.50±0.05

WHITE SILK LINE

6.00 ±0.30
STIFFENER

3.55

NOTE
1 DISPLAY MODULE 10.2″ ARRAY FOR EPD
2 DRIVER IC:SSD1677
3 RESOLUTION: 640gateX960source
4 PIXEL SIZE:0.2245mmX0.2245mm

RoHS

TOLERANCES UNMARKED ANGLES±5°	TITLE:	PROJECT:	REV.:	DATE:	CUST. P/N:
	EPD	GDEM102T91	A	23.06.15	
.X=±0.4mm	DWN.	CHK.	APPR.	UNIT:	3RD ANGLE:	PAGE:
.XX=±0.20mm	NN ZHAO	CC ZHENG	XF NIE	mm	⊕◁	1/1
.XXX=±0.20mm						

5. Input/output Pin Assignment

No.	Name	I/O	Description	Remark
1	NC		Do not connect with other NC pins	Keep Open
2	GDR	O	N-Channel MOSFET Gate Drive Control	
3	RESE	I	Current Sense Input for the Control Loop	
4	NC	NC	Do not connect with other NC pins	Keep Open
5	VSH	C	Positive Source driving voltage	
6	TSCL	O	I2C Interface to digital temperature sensor Clock pin	Note 5-6
7	TSDA	I/O	I2C Interface to digital temperature sensor Data pin	Note 5-6
8	BS1	I	Bus Interface selection pin	Note 5-5
9	BUSY	O	Busy state output pin	Note 5-4
10	RES#	I	Reset signal input. Active Low.	Note 5-3
11	D/C#	I	Data /Command control pin	Note 5-2
12	CS#	I	Chip select input pin	Note 5-1
13	SCL	I	Serial Clock pin (SPI)	
14	SDA	I/O	Serial Data pin (SPI)	
15	VDDIO	P	Power Supply for interface logic pins It should be connected with VCI	
16	VCI	P	Power Supply for the chip	
17	VSS	P	Ground	
18	VDD	C	Core logic power pin VDD can be regulated internally from VCI. A capacitor should be connected between VDD and VSS	
19	VPP	P	FOR TEST	Keep Open
20	VSH1	C	Positive Source driving voltage	
21	VGH	C	Power Supply pin for Positive Gate driving voltage and VSH1	
22	VSL	C	Negative Source driving voltage	
23	VGL	C	Power Supply pin for Negative Gate driving voltage VCOM and VSL	
24	VCOM	C	VCOM driving voltage	

I = Input Pin, O =Output Pin, I/O = Bi-directional Pin (Input/output), P = Power Pin, C = Capacitor Pin

Note 5-1: This pin (CS#) is the chip select input connecting to the MCU.   The chip is enabled for MCU communication only when CS# is pulled LOW.

Note 5-2: This pin is (D/C#) Data/Command control pin connecting to the MCU in 4-wire SPI mode.   When the pin is pulled HIGH, the data at SDA will be interpreted as data. When the pin is pulled LOW, the data at SDA will be interpreted as command.

Note 5-3: This pin (RES#) is reset signal input. The Reset is active low.

Note 5-4: This pin is Busy state output pin. When Busy is High, the operation of chip should not be interrupted, command should not be sent. The chip would put Busy pin High when -Outputting display waveform -Communicating with digital temperature sensor

Note 5-5: Bus interface selection pin

Note 5-6:This pin connect to the VSS if there is no external temperature sensor.

BS1 State	MCU Interface
L	4-lines serial peripheral interface(SPI) - 8 bits SPI
H	3- lines serial peripheral interface(SPI) - 9 bits SPI

6. Electrical Characteristics

6.1 Absolute Maximum Rating

| Parameter	Symbol	Rating	Unit
Logic supply voltage	VCI	-0.5 to +4.0	V
Logic Input voltage	VIN	-0.5 to VCI +0.5	V
Logic Output voltage	VOUT	-0.5 to VCI +0.5	V
Operating Temp range	TOPR	0 to +50	℃.
Storage Temp range	TSTG	-25 to+70	℃.
Optimal Storage Temp	TSTGo	23±3	℃.
Optimal Storage Humidity	HSTGo	55±10	%RH

Note:

Maximum ratings are those values beyond which damages to the device may occur.

Functional operation should be restricted to the limits in the Panel DC Characteristics tables.

6.2 Panel DC Characteristics

The following specifications apply for: VSS=0V, VCI=3.0V, TOPR =25ºC.

Parameter	Symbol	Condition	Applicable pin	Min.	Typ.	Max.	Unit
Single ground	V_{SS}	-		-	0	-	V
Logic supply voltage	V_{CI}	-	VCI	2.2	3.0	3.7	V
Core logic voltage	V_{DD}		VDD	1.7	1.8	1.9	V
High level input voltage	V_{IH}	-	-	0.8 V_{CI}	-	-	V
Low level input voltage	V_{IL}	-	-	-	-	0.2 V_{CI}	V
High level output voltage	V_{OH}	IOH = -100uA	-	0.9 V_{CI}	-	-	V
Low level output voltage	V_{OL}	IOL = 100uA	-	-	-	0.1 V_{CI}	V
Typical power	P_{TYP}	V_{CI}=3.0V	-	-	48	-	mW
Deep sleep mode	P_{STPY}	V_{CI}=3.0V	-	-	0.003	-	mW
Typical operating current	Iopr_VCI	V_{CI}=3.0V	-	-	16	-	mA
Typical peak current	Iopr_VCI	2.3~3.6V			100	160	mA
Full update time	-	25 ℃	-	-	4	-	Sec
Partial update time	-	25 ℃	-	-	0.42	-	Sec
Sleep mode current	Islp_VCI	DC/DC off No clock No input load Ram data retain	-	-	20	-	uA
Deep sleep mode current	Idslp_VCI	DC/DC off No clock No input load Ram data not retain	-	-	3	5	uA

Notes: 1. The typical power is measured with following transition from horizontal 2 scale pattern to vertical 2 scale pattern.
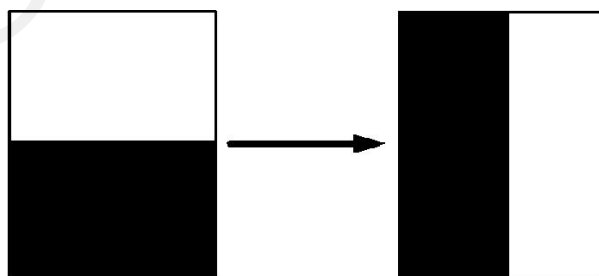
2. The deep sleep power is the consumed power when the panel controller is in deep sleep mode.

3. The listed electrical characteristics are only guaranteed under the controller & waveform provided by Good Display.

4. Electrical measurement：Tektronix oscilloscope - MDO3024，Tektronix current probe–TCP0030A.

6.3 Panel DC Characteristics(Driver IC Internal Regulators)

The following specifications apply for: VSS=0V, VCI=3.0V, TOPR =25ºC.

Parameter	Symbol	Condition	Applicable pin	Min.	Typ.	Max.	Unit
VCOM output voltage	VCOM	-	VCOM	-	TBD	-	V
Positive Source output voltage	V_{SH}	-	$S_0 \sim S_{959}$	+14.5	+15	+15.5	V
Negative Source output voltage	V_{SL}	-	$S_0 \sim S_{959}$	-15.5	-15	-14.5	V
Positive gate output voltage	Vgh	-	$G_0 \sim G_{639}$	+19	+20	+21	V
Negative gate output voltage	Vgl	-	$G_0 \sim G_{639}$	-21	-20	-19	V

6.4 Panel AC Characteristics
6.4.1 MCU Interface Selection

The pin assignment at different interface mode is summarized in Table 6-4-1. Different MCU mode can be set by hardware selection on BS1 pins. The display panel only supports 4-wire SPI or 3-wire SPI interface mode.

| Pin Name	Data/Command Interface		Control Signal		
Bus interface	SDA	SCL	CS#	D/C#	RES#
BS1=L 4-wire SPI	SDA	SCL	CS#	D/C#	RES#
BS1=H 3-wire SPI	SDA	SCL	CS#	L	RES#

6.4.2 MCU Serial Interface (4-wire SPI)

The serial interface consists of serial clock SCL, serial data SDA, D/C#, CS#. This interface supports Write mode and Read mode.

Function	CS#	D/C#	SCL
Write command	L	L	↑
Write data	L	H	↑

Note: ↑ stands for rising edge of signal

In the write mode SDA is shifted into an 8-bit shift register on every rising edge of SCL in the order of D7, D6, ... D0. The level of D/C# should be kept over the whole byte . The data byte in the shift register is written to the Graphic Display Data RAM /Data Byte register or command Byte register according to D/C# pin.

Figure 6-1: Write procedure in 4-wire SPI mode
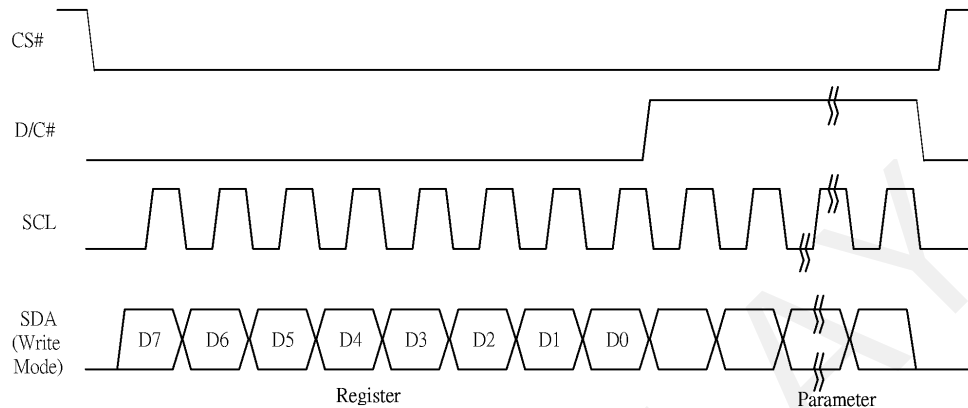
In the Read mode:

1. After driving CS# to low, MCU need to define the register to be read.

2. SDA is shifted into an 8-bit shift register on every rising edge of SCL in the order of D7, D6, ... D0 with D/C# keep low.

3. After SCL change to low for the last bit of register, D/C# need to drive to high.

4. SDA is shifted out an 8-bit data on every falling edge of SCL in the order of D7, D6, … D0.

5. Depending on register type, more than 1 byte can be read out. After all byte are read, CS# need to drive to high to stop the read operation.

Figure 6-2: Read procedure in 4-wire SPI mode
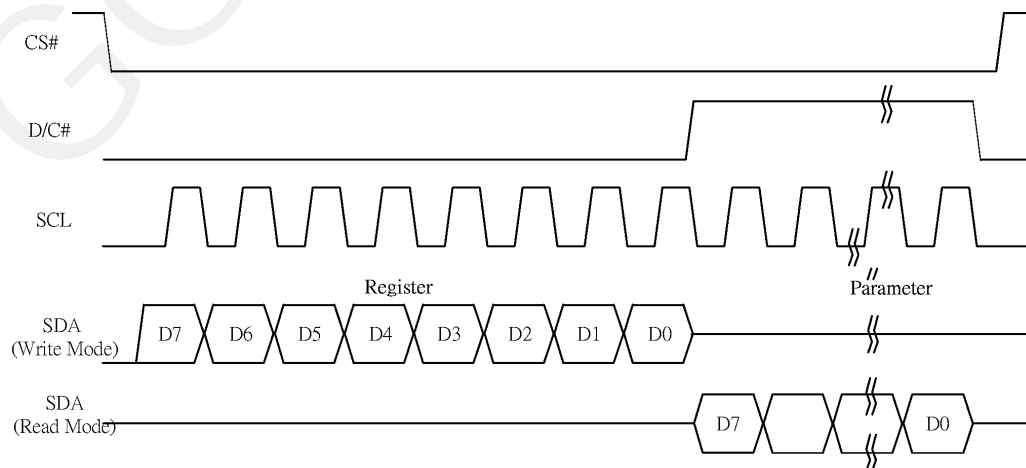
## 6.4.3 MCU Serial Interface (3-wire SPI)

The 3-wire serial interface consists of serial clock SCL, serial data SDA and CS#. This interface also supports Write mode and Read mode.

The operation is similar to 4-wire serial interface while D/C# pin is not used. There are altogether 9-bits will be shifted into the shift register on every ninth clock in sequence: D/C# bit, D7 to D0 bit.   The D/C# bit (first bit of the sequential data) will determine the following data byte in the shift register is written to the Display Data RAM (D/C# bit = 1) or the command register (D/C# bit = 0).

| Function	CS#	D/C#	SCL
Write command	L	Tie	↑
Write data	L	Tie	↑

Note：↑ stands for rising edge of signal

Figure 6-3: Write procedure in 3-wire SPI mode
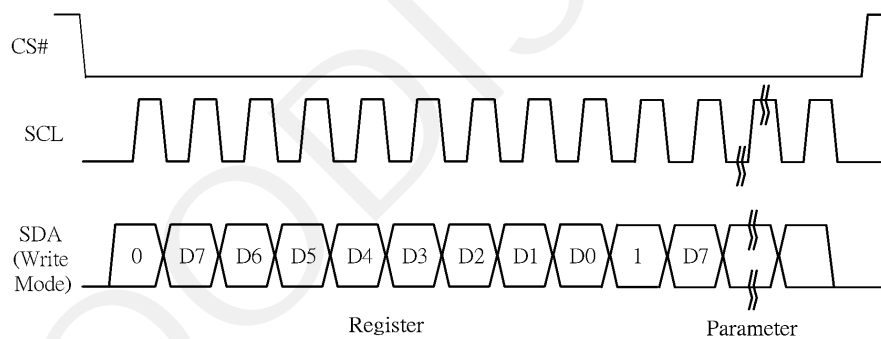
In the Read mode:

1. After driving CS# to low, MCU need to define the register to be read.

2. D/C=0 is shifted thru SDA with one rising edge of SCL

3. SDA is shifted into an 8-bit shift register on every rising edge of SCL in the order of D7, D6, ... D0.

4. D/C=1 is shifted thru SDA with one rising edge of SCL

5. SDA is shifted out an 8-bit data on every falling edge of SCL in the order of D7, D6, … D0.

6. Depending on register type, more than 1 byte can be read out. After all byte are read, CS# need to drive to high to stop the read operation.

Figure 6-4: Read procedure in 3-wire SPI mode
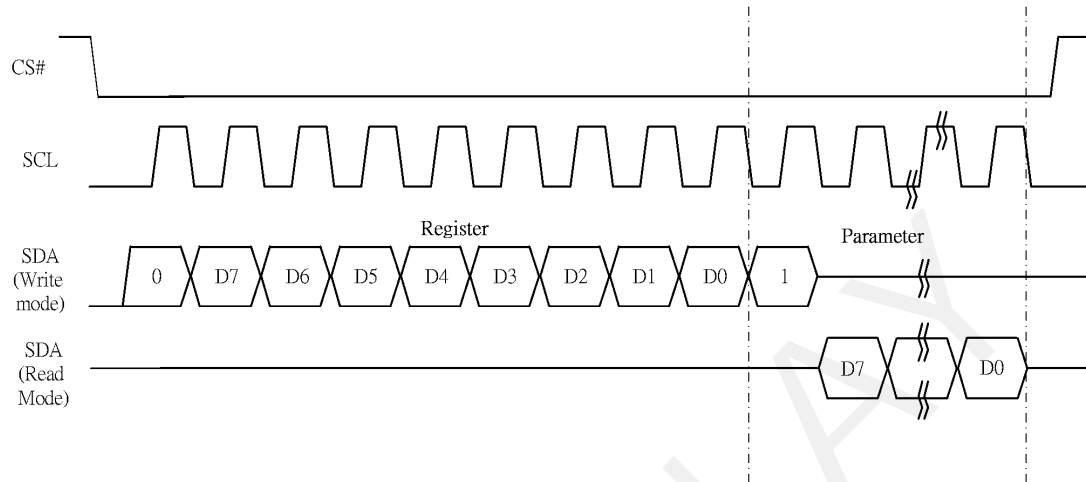
6.4.4 Interface Timing

The following specifications apply for: VSS=0V, VCI=3.0V, TOPR =25ºC.
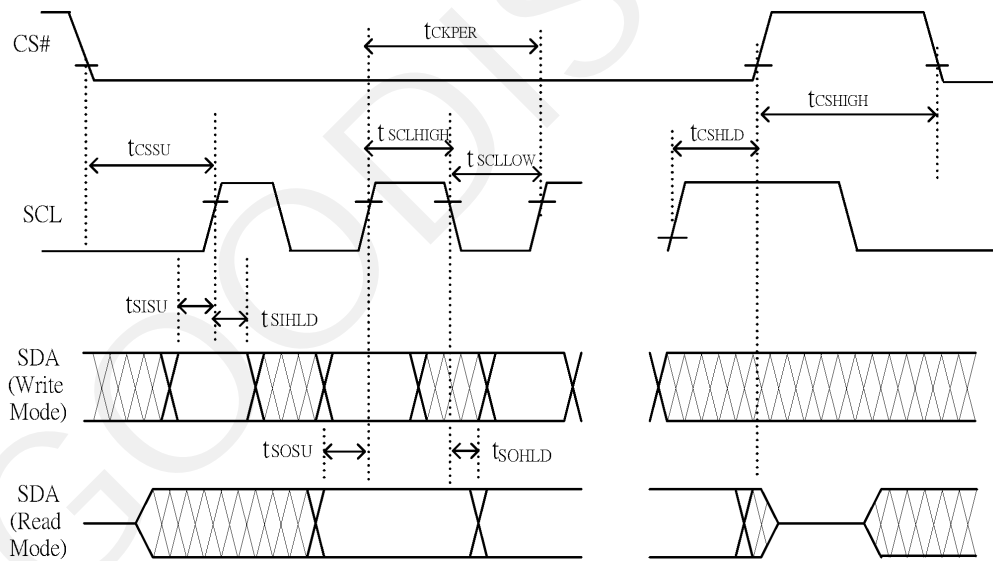
Changed Diagram

Serial Interface Timing Characteristics
(VCI - VSS = 2.2V to 3.7V, TOPR = 25°C, CL=20pF)

Write mode

Symbol	Parameter	Min	Typ.	Max	Unit
fSCL	SCL frequency (Write Mode)			20	MHz
tCSSU	Time CS# has to be low before the first rising edge of SCLK	20			ns
tCSHLD	Time CS# has to remain low after the last falling edge of SCLK	20			ns
tCSHIGH	Time CS# has to remain high between two transfers	100			ns
tSCLHIGH	Part of the clock period where SCL has to remain high	25			ns
tSCLLOW	Part of the clock period where SCL has to remain low	25			ns
tSISU	Time SI (SDA Write Mode) has to be stable before the next rising edge of SCL	10			ns
tSIHLD	Time SI (SDA Write Mode) has to remain stable after the rising edge of SCL	40			ns

Read mode

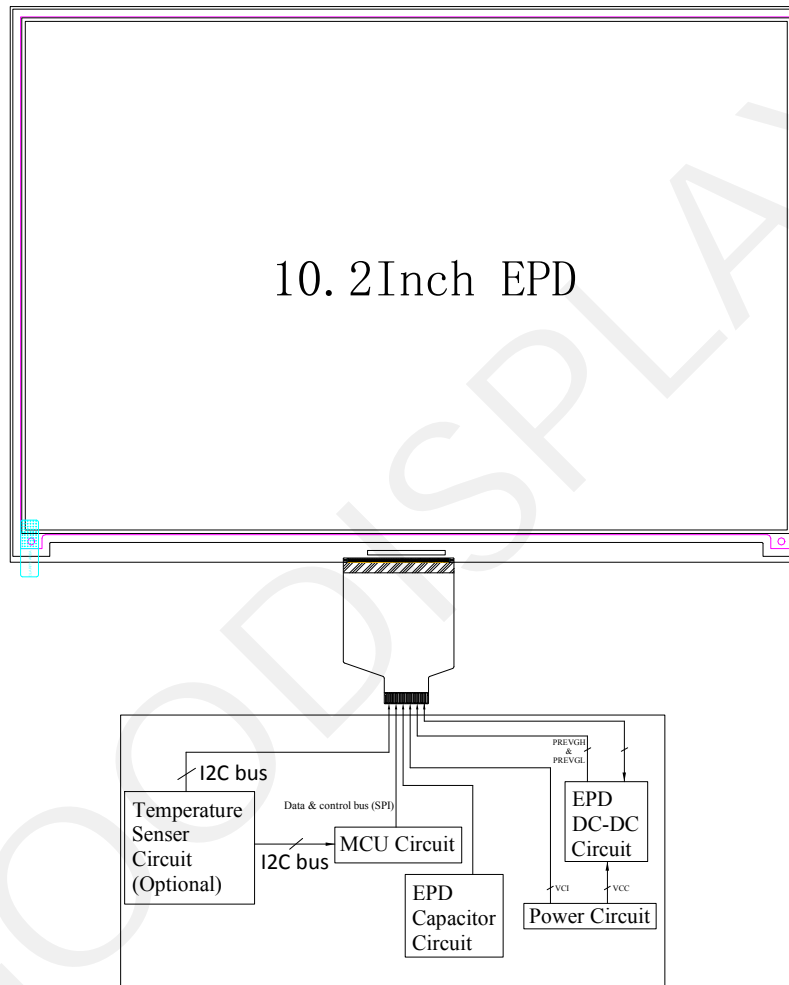| Symbol	Parameter	Min	Typ.	Max	Unit
fSCL	SCL frequency (Read Mode)			2.5	MHz
tCSSU	Time CS# has to be low before the first rising edge of SCLK	100			ns
tCSHLD	Time CS# has to remain low after the last falling edge of SCLK	50			ns
tCSHIGH	Time CS# has to remain high between two transfers	250			ns
tSCLHIGH	Part of the clock period where SCL has to remain high	180			ns
tSCLLOW	Part of the clock period where SCL has to remain low	180			ns
tSOSU	Time SO(SDA Read Mode) will be stable before the next rising edge of SCL		50		ns
tSOHLD	Time SO (SDA Read Mode) will remain stable after the rising edge of SCL		0		ns

7.Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	01	0	0	0	0	0	0	0	1	Driver Output control	Gate setting
0	1		A7	A6	A5	A4	A3	A2	A1	A0		Set A[9:0]=27Fh[POR] ,640MUX
0	1		0	0	0	0	0	0	A9	A8		Set B[2:0]=000[POR]
0	1		0	0	0	0	0	B2	B1	B0		
0	0	03	0	0	0	0	0	0	1	1	Gate Driving voltage control	Set Gate Driving voltage
0	1		0	0	0	A4	A3	A2	A1	A0		A[4:0]=17h[POR],VGH at 20V[POR] VGH setting from 12V to 20V
0	0	04	0	0	0	0	0	1	0	0	Source Driving voltage control	Set Source Driving voltage
0	1		A7	A6	A5	A4	A3	A2	A1	A0		A[7:0]= 41h[POR],VSH1 at 15V
0	1		B7	B6	B5	B4	B3	B2	B1	B0		B[7:0]=A8h[POR],VSH2 at 5.0V
0	1		C7	C6	C5	C4	C3	C2	C1	C0		C[7:0]= 32h[POR], VSL at -15V
0	0	10	0	0	0	1	0	0	0	0	Deep Sleep mode	Deep Sleep mode Control
0	1		0	0	0	0	0	0	A_1	A_0		A[1:0] : / Description; 00 / Normal Mode [POR]; 11 / Enter Deep Sleep Mode. After this command initiated, the chip will enter Deep Sleep Mode, BUSY pad will keep output high.
0	0	11	0	0	0	1	0	0	0	1	Data Entry mode setting	Define data entry sequence
0	1		0	0	0	0	0	A_2	A_1	A_0		A [1:0] = ID[1:0]Address automatic increment / decrement setting. The setting of incrementing or decrementing of the address counter can be made independently in each upper and lower bit of the address. 00 –Y decrement, X decrement, 01 –Y decrement, X increment, 10 –Y increment, X decrement, 11 –Y increment, X increment [POR] A[2] = AM Set the direction in which the address counter is updated automatically after data are written to the RAM. AM= 0, the address counter is updated in the X direction. [POR] AM = 1, the address counter is updated in the Y direction.
0	0	12	0	0	0	1	0	0	1	0	SWRESET	It resets the commands and parameters to their S/W Reset default values except R10h-Deep Sleep Mode During operation ,BUSY pad will output high. Note: RAM are unaffected by this command.

0	0	18	0	0	0	1	1	0	0	0	Temperature Sensor Control	Temperature Sensor Selection A[7:0] = 48h [POR], external temperature sensor A[7:0] = 80h Internal temperature sensor
0	1		A7	A6	A5	A4	A3	A2	A1	A0		
0	0	1A	0	0	0	1	1	0	1	0	Temperature Sensor Control (Write to temperature register)	Write to temperature register. A[11:0]=7FFh[POR]
0	1		A11	A10	A9	A8	A7	A6	A5	A4		
0	1		A3	A2	A1	A0	0	0	0	0		
0	0	20	0	0	1	0	0	0	0	0	Master Activation	Activate Display Update Sequence The Display Update Sequence Option is located at R22h User should not interrupt this operation to avoid corruption of panel images.
0	0	21	0	0	1	0	0	0	0	1	Display Update Control 1	RAM content option for Display Update A[7:0]=00h[POR] A[7:4] Red RAM option
0	1		A7	A6	A5	A4	A3	A2	A1	A0		

0000	Normal
0100	Bypass RAM content as 0
1000	Inverse RAM content

A[3:0] BW RAM option

0000	Normal
0100	Bypass RAM content as 0
1000	Inverse RAM content

0	0	22	0	0	1	0	0	0	1	0	Display Update Control 2	Display Update Sequence Option: Enable the stage for Master Activation
	1		A7	A6	A5	A4	A3	A2	A1	A0		

Setting for LUT from MCU

Enable Clock Signal, Then Enable Analog Then PATTERN DISPLAY Then Disable Analog Then Disable OSC	C7

Setting for LUT from OTP according to external Temperature Sensor operation

Then Enable Analog Then Load LUT	90
Enable Analog Then PATTERN DISPLAY Then Disable Analog Then Disable OSC	47

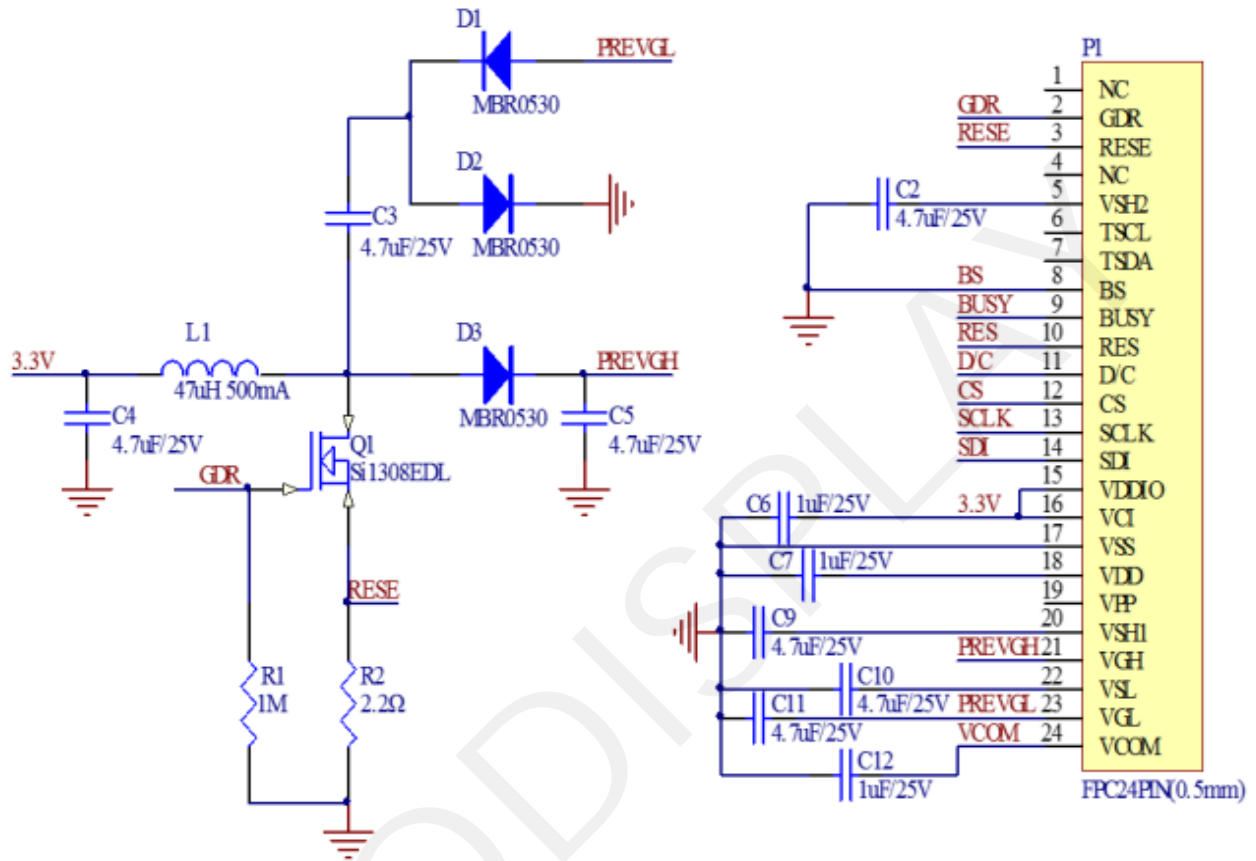|												
0	0	24	0	0	1	0	0	1	0	0	Write RAM (BW)	After this command, data entries will be written into the 1RAM until another command is written. Address pointers will advance accordingly. For Write pixel: Content of write RAM(BW)=1 For Black pixel: Content of write RAM(BW)=0

0	0	26	0	0	1	0	0	1	1	0	Write RAM (RED)	After this command, data entries will be written into the 2 RAM until another command is written. Address pointers will advance accordingly. For RED pixel: Content of write RAM(RED)=1 For White/Black pixel: Content of write RAM(RED)=0
0	0	2C	0	0	1	0	1	1	0	0	Write VCOM register	Set A[7:0]=50h
0	1		A7	A6	A5	A4	A3	A2	A1	A0		
0	0	2D	0	0	1	0	1	1	0	1	OTP Register Read	Read Register stored in OTP: 1. A[7:0]~ B[7:0]: VCOM Information 2. C[7:0]~G[7:0]:Display mode 3. H[7:0]~K[7:0]: Waveform Version [4bytes]
1	1		A7	A6	A5	A4	A3	A2	A1	A0		
1	1		B7	B6	B5	B4	B3	B2	B1	B0		
1	1		C7	C6	C5	C4	C3	C2	C1	C0		
1	1		D7	D6	D5	D4	D3	D2	D1	D0		
1	1		E7	E6	E5	E4	E3	E2	E1	E0		
1	1		F7	F6	F5	F4	F3	F2	F1	F0		
1	1		G7	G6	G5	G4	G3	G2	G1	G0		
1	1		H7	H6	H5	H4	H3	H2	H1	H0		
1	1		I7	I6	I5	I4	I3	I2	I1	I0		
1	1		J7	J6	J5	J4	J3	J2	J1	J0		
1	1		K7	K6	K5	K4	K3	K2	K1	K0		
0	0	2F	0	0	1	0	1	1	1	1	Status Bit Read	Read IC status Bit [POR 0x21] A[5]: HV Ready Detection flag [POR=1] 0: Ready 1: Not Ready A[4]: VCI Detection flag [POR=0] 0: Normal 1: VCI lower than the Detect level A[3]: [POR=0] A[2]: Busy flag [POR=0] 0: Normal 1: BUSY A[1:0]: Chip ID [POR=01] Remark: A[5] and A[4] status are not valid after RESET, they need to be initiated by command 0x14 and command 0x15 respectively.
1	1		0	0	A5	A4	0	0	A1	A0		
0	0	32	0	0	1	1	0	0	1	0	Write LUT register	Write LUT register from MCU interface [105 bytes].
0	1		A7	A6	A5	A4	A3	A2	A1	A0		
0	1		B7	B6	B5	B4	B3	B2	B1	B0		
0	1		:	:	:	:	:	:	:	:		
0	1		:	:	:	:	:	:	:	:		
0	1		:	:	:	:	:	:	:	:		

			D7	D6	D5	D4	D3	D2	D1	D0		
0	0	3A	0	0	1	1	1	0	1	0	Reserved	Reserved
0	0	3B	0	0	1	1	1	0	1	1	Reserved	Reserved
0	0	3C	0	0	1	1	1	1	0	0	Border Waveform Control	Select border waveform for VBD
0	1		A_7	A_6	A_5	A_4	0	0	A_1	A_0		A [7:0]=C0h[POR],set VBD as HIZ

A [7:6] Select VBD option

A[7:6]	Select VBD as
00	GS Transition Define A[1:0]
01	Fix Level Define A [5:4]
10	VCOM
11[POR]	HIZ

A [5:4] Fix Level Setting for VBD

A[5:4]	VBD level
00[POR]	VSS
01	VSH1
10	VSL
11	VSH2

A[1:0]) BW Transition setting for VBD

A[1:0]	VBD Transition
00 [POR]	LUT0
01	LUT1
10	LUT2
11	LUT3

			D7	D6	D5	D4	D3	D2	D1	D0		
0	0	44	0	1	0	0	0	1	0	0	Set RAM X -address Start / End position	Specify the start/end positions of the window address in the X direction by an address unit A[9:0]: XSA[9:0], X Start, POR = 000h B[9:0]: XEA[9:0], X End, POR = 3BFh
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		-	-	-	-	-	-	A_9	A_8		
0	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
0	1		-	-	-	-	-	-	B_9	B_8		
0	0	45	0	1	0	0	0	1	0	1	Set Ram Y-address Start / End position	Specify the start/end positions of the window address in the Y direction by an address unit A[9:0]: YSA[9:0], Y Start, POR = 000h B[9:0]: YEA[9:0], Y End, POR = 27Fh
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		-	-	-	-	-	-	A_9	A_8		
0	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
0	1		-	-	-	-	-	-	B_9	B_8		
0	0	4E	0	1	0	0	1	1	1	0	Set RAM X address counter	Make initial settings for the RAM X address in the address counter (AC) A[9:0]: 000h[POR]
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		-	-	-	-	-	-	A_9	A_8		
0	0	4F	0	1	0	0	1	1	1	1	Set RAM Y address counter	Make initial settings for the RAM Y address in the address counter (AC) A[9:0]: 000h[POR]
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		-	-	-	-	-	-	A_9	A_8		
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		

8. Block Diagram

10.2Inch EPD

I2C bus

Temperature
Senser
Circuit
(Optional)

Data & control bus (SPI)

I2C bus

MCU Circuit

EPD
Capacitor
Circuit

PREVGH
&
PREVGL

EPD
DC-DC
Circuit

VCI   VCC

Power Circuit

9.Typical Application Circuit with SPI Interface

10.Typical Operating Sequence

10.1 LUT from OTP Operation Flow

```
                    ┌─────────────────────┐
                    │      Power On        │
              ┌────>│    (Apply VCI)       │
              │     └─────────────────────┘
              │                │
              │                ▼
              │     ┌─────────────────────┐
              │     │ Reset the EPD driver IC │<────────────┐
              │     └─────────────────────┘                 │
              │                │                             │
              │                ▼                             │
              │     ┌─────────────────────┐                 │
              │     │ Turn on the oscillator clock │         │
              │     │ and DC/DC regulator to │               │
              │     │ generate the drive voltage │           │
              │     └─────────────────────┘                 │
              │                │                             │
              │                ▼                             │
              │     ┌─────────────────────┐                 │
              │     │ Define the display size and │          │
              │     │ RAM address 、border │                 │
              │     └─────────────────────┘                 │
              │                │                             │
              │                ▼                             │
              │     ┌─────────────────────┐                 │
              │     │ LUT written from MCU │                 │
              │     └─────────────────────┘                 │
              │                │                             │
              │                ▼                             │
              │     ┌─────────────────────┐                 │
              │     │ Load image data and update │           │
              │     └─────────────────────┘                 │
              │                │                             │
              │         ┌──────┴──────┐                      │
              │         ▼             ▼                      │
        ┌──────────┐          ┌──────────────┐              │
        │ Power Off │          │  Enter into  │─────────────┘
        └──────────┘          │  deep sleep  │
                              └──────────────┘
```
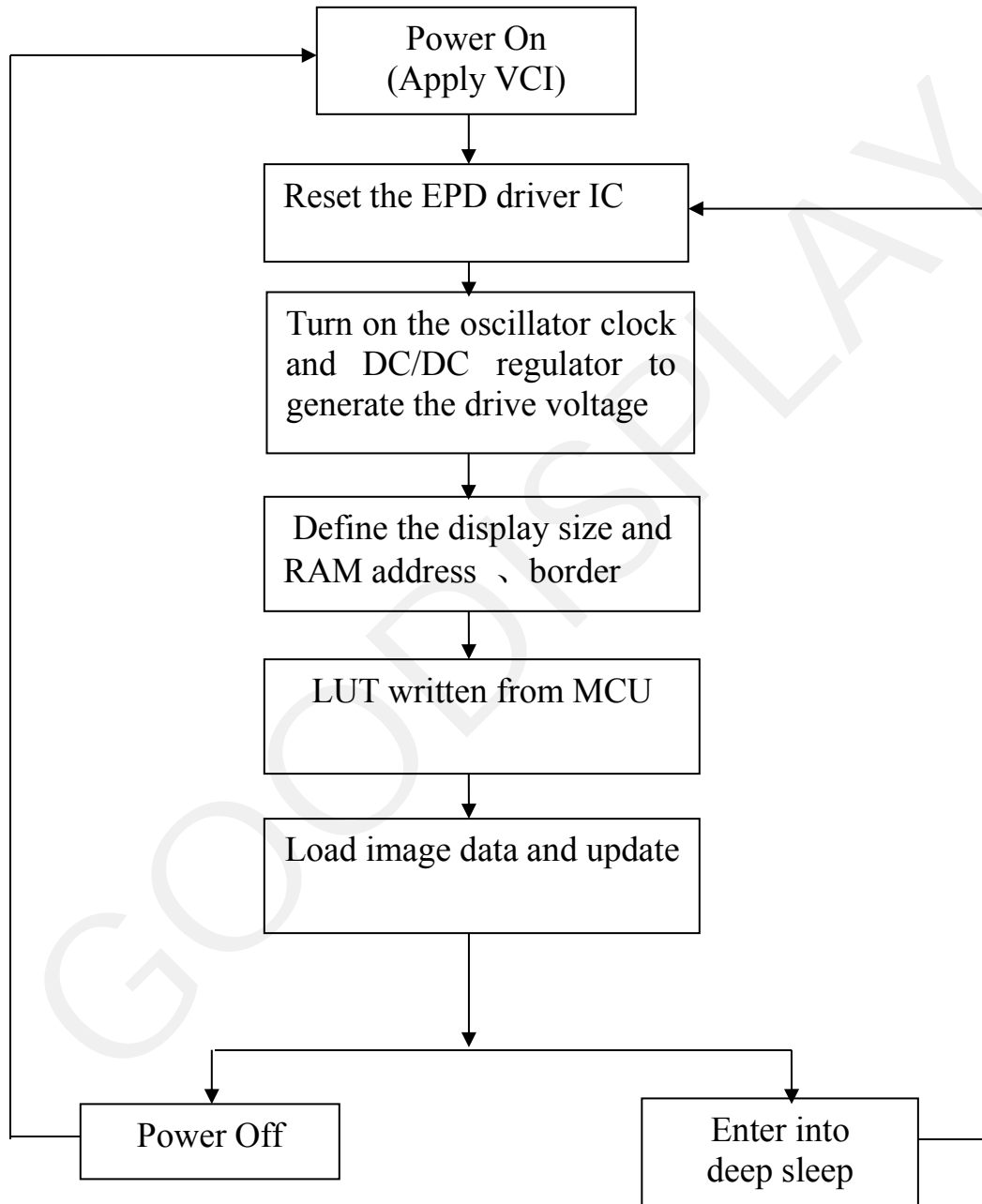
10.2 LUT from OTP Operation Reference Program Code

ACTION	VALUE/DATA	COMMENT
POWER ON		
delay	10ms	
PIN CONFIG		
RES#	low	Hardware reset
delay	200us	
RES#	high	
delay	200us	
Read busy pin		Wait for busy low
Command 0x12		Software reset
Read busy pin		Wait for busy low
Command 0x01	Data 0x7F 0x02 0x00	Set display size and driver output control
Command 0x11	Data 0x01	Ram data entry mode
Command 0x44	Data 0x00 0x00 0xBF 0x03	Set Ram X address
Command 0x45	Data 0x7F 0x02 0x00 0x00	Set Ram Y address
Command 0x3C	Data 0x01	Set border
SET VOLTAGE AND LOAD LUT		
Command 0x2C	Data 0x50	Set VCOM value
Command 0x03	Data 0x17	Gate voltage setting
Command 0x04	Data 0x41 0xB0 0x32	Source voltage setting
Command 0x32	Write 105bytes LUT	Load LUT
LOAD IMAGE AND UPDATE		
Command 0x4E	Data 0x00 0x00	Set Ram X address counter
Command 0x4F	Data 0x7F 0x02	Set Ram Y address counter
Command 0x24	76800 bytes	Load BW image (960/8*640)
Command 0x22	Data 0xC7	Image update
Command 0x20		
Read busy pin		Wait for busy low
Command 0x10	Data 0x01	Enter deep sleep mode
POWER OFF		

11. Reliability Test

NO	Test items	Test condition
1	Low-Temperature Storage	T = -25°C, 240 h Test in white pattern
2	High-Temperature Storage	T = +70°C, RH=40% ,240h Test in white pattern
3	High-Temperature Operation	T = +50°C, RH = 30% ,240h
4	Low-Temperature Operation	0ºC，240h
5	High-Temperature, High-Humidity Operation	T=+40ºC，RH=90%,240h
6	High Temperature, High Humidity Storage	T=+60ºC，RH=80%,240h Test in white pattern
7	Temperature Cycle	1 cycle:[-25°C 30min]→[+70 °C 30 min] : 100 cycles Test in white pattern
8	ESD Gun	Air+/-4KV;Contact+/-2KV Contact+/-2KV(HBM C:100pF;R:1.5k ohm) Contact+/-200V(MM C:200pF;R:0 ohm) (Naked EPD display,including IC and FPC area)
9	UV exposure Resistance	765W/m² for 168hrs,40℃ Test in white pattern

Note：1. Stay white pattern for storage and non-operation test.

2. Operation is black→white pattern, the interval is 150s.

12.Quality Assurance

12.1 Environment

Temperature：23±3℃

Humidity：55±10%RH

12.2 Illuminance

Brightness:1200～1500LUX;distance:20-30CM;Angle:Relate 45°surround.

12.3 Inspect method
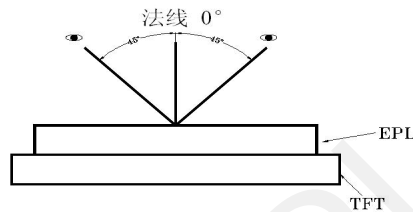
12.4 Display area
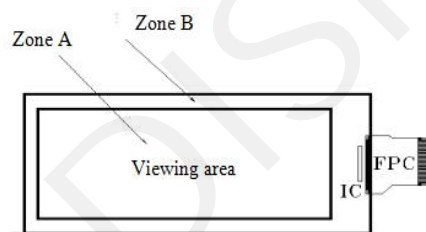
12.5 Ghosting test method

Two-color ghosting is measured with following transition from horizontal 2 scale pattern to vertical 2 scale pattern.

The listed optical characteristics are only guaranteed under the controller & waveform provided by Good Display.
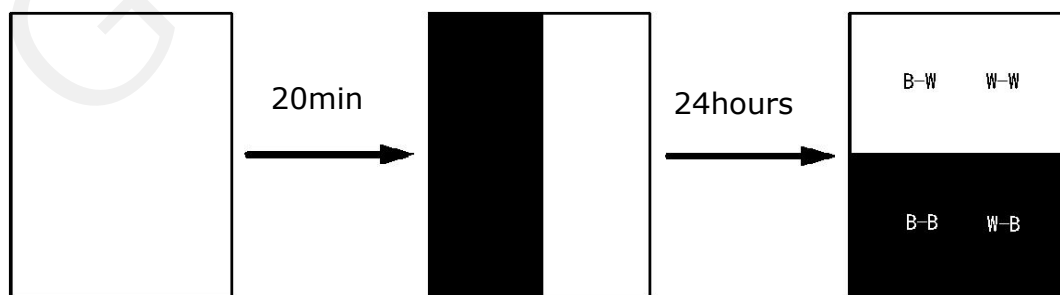
1)Measurement Instruments：X-rite i1Pro
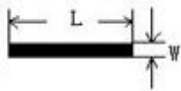
2)Ghosting formula:
W ghosting：△L= Max (ΔL(W-W, B-W)) - Min (ΔL(W-W B-W))
K ghosting：△L= Max (ΔL(W-B, B-B)) - Min(ΔL(W-B, B-B))
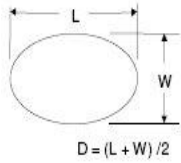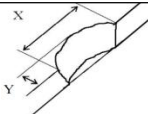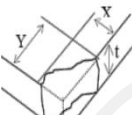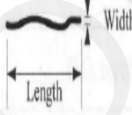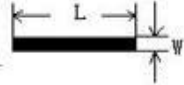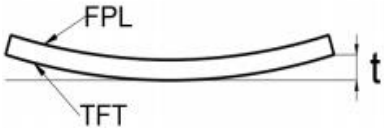
12.6 Inspection standard

12.6.1 Electric inspection standard

NO.	Item	Standard	Defect level	Method	Scope
1	Display	Clear display Display complete Display uniform	MA	Visual inspection	Zone A
2	Black/White spots	 D≤0.4mm，Allowed 0.4mm＜D≤0.7mm。N≤6， 0.7mm＜D　Not Allow	MI	Visual inspection	Zone A
3	Black/White spots (No switch)	 L≤2.0mm,W≤0.2mm　negligible 2.0mm＜L≤8.0mm 0.2mm＜W≤0.5mm N≤5 allowable L＞8.0mm ,W＞0.5mm is not allowed		Visual/ Inspection card	
4	Ghost image	Allowed in switching process	MI	Visual inspection	
5	Flash dot / Multilateral	Flash points are allowed when switching screens Multilateral colors outside the frame are allowed for fixed screen time	MI	Visual/ Inspection card	Zone A Zone B
6	Segmented display	Selection segments are all displayed, and other segments are not displayed after the selection segment.	MA	Visual inspection	Zone A
7	Short circuit/ Circuit break/ Abnormal Display	Not Allow			

12.6.2 Appearance inspection standard

NO.	Item	Standard	Defect level	Method	Scope
1	B/W spots /Bubble/ Foreign bodies/ Dents	D≤0.4mm，negligible 0.4mm＜D≤0.7mm，N≤6，Allowed D＞0.7mm，Not Allow	MI	Visual inspection	Zone A
2	Glass crack	Not Allow	MA	Visual / Microscope	Zone A Zone B
3	\Dirty	Allowed if can be removed	MI		Zone A Zone B
4	Chips/Scratch/ Edge crown	X≤3mm,Y≤0.5mm 2mm≤X or 2mm≤Y Allow W≤0.1mm,L≤5mm, n≤ 2	MI	Visual / Microscope	Zone A Zone B
5	TFT Cracks	Not Allow	MA	Visual / Microscope	Zone A Zone B
6	Dirty/ foreign body	Allowed if can be removed/ allow	MI	Visual / Microscope	Zone A / Zone B
7	FPC broken/ FPC oxidation / scratch	Not Allow	MA	Visual / Microscope	Zone B

8	B/W Line	 L≤2.0mm,W≤0.2mm negligible 2.0mm＜L≤8.0mm 0.2mm＜W≤0.5mm N≤5 allowable L＞8.0mm ,W＞0.5mm is not allowed	MI	Visual / Ruler	Zone B

9	TFT edge bulge /TFT chromatic aberration	TFT edge bulge：
		  X≤3mm，Y≤0.3mm Allowed
		  TFT chromatic aberration :Allowed
			MI	Visual / Microscope	Zone A Zone B

10	Electrostatic point	D≤0.3mm, negligible 0.3mm＜D≤0.5mm ,n≤4 allow D＞0.5mm is not allowed (n≤10 items are allowed within 5 mm in diameter)	MI	Visual / Microscope	Zone A
11	PCB damaged/ Poor welding/ Curl	PCB（Circuit area）damaged Not Allow PCB Poor welding Not Allow PCB Curl≤1%	MI	Visual / Ruler	
12	Edge glue height/ Edge glue bubble	Edge Adhesives H≤PS surface (Including protect film) Edge adhesives seep in≤1/2 Margin width Length excluding Edge adhesives bubble：bubble Width ≤1/2 Margin width；Length ≤5.0mm。n≤5	MI		Zone B
13	Protect film	Surface scratch but not effect protect function, Allow	MI	Visual Inspection	Zone B
14	Silicon glue	Thickness ≤ PS surface(With protect film): Full cover the IC; Shape: The width on the FPC≤0.5mm (Front) The width on the FPC≤1.0mm (Back) smooth surface, No obvious raised.	MI	Visual Inspection	
15	Warp degree (TFT substrate)	 t≤2.5mm	MI	Ruler	
16	Color difference in COM area (Silver point area)	Allowed		Visual Inspection	

13. Packaging

EPD PACKING INSTRUCTION		DATE	
		DESIGN	
		CHECKED	
		APPROVED	
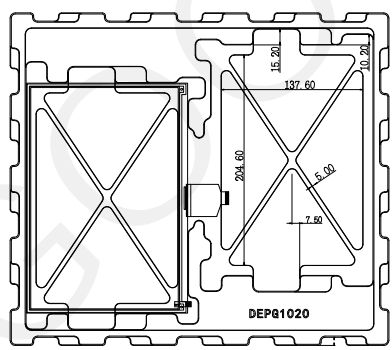
P/N	Customer Code	Ref.P/N		Type	PKG Method	Marking	Surface Marks	Pull Tape	
GDEM102T91				GLASS	Blister	BACK	None	YES	

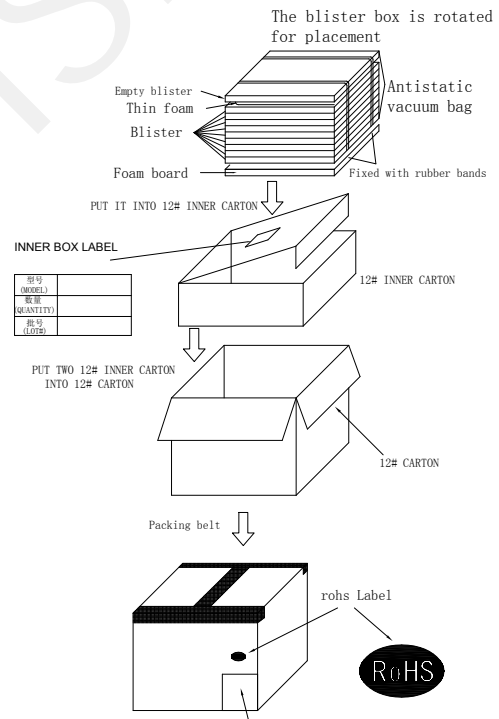| Packing Materials List					2PCS/LAYER, 18LAYER/CTN, TOTAL 36PCS/CTN.
List	Model	Materials	Q'ty	Unit	
Carton	12# 417*362*229 mm	corrugate	1	Piece	Pull tape:
Inner Carton	12#(INNER)400*343 *95 mm	corrugate	2	Piece	
Blister		PET	20	Piece	
Thin foam	335.8*259.6*T1.5~1.8MM	EPE	18	Piece	
Antistatic vacuum bag	450*590*0.075		2	Piece	
Foam board		EPE	3	Piece	
PULL TAPE	16*5*T0.05		36	Piece	

Detail:

Blister box:

Note: there are 18 layers of products, divided into 2 inner boxes, and an empty blister box is placed on the top of each inner box, so the number of blister boxes is 20

DEPG1020

QUANTITY: 2PCS

The blister box is rotated for placement

Empty blister
Thin foam
Blister
Foam board
Antistatic vacuum bag
Fixed with rubber bands

PUT IT INTO 12# INNER CARTON

INNER BOX LABEL

型号 (MODEL)	
数量 (QUANTITY)	
批号 (LOT№)	

12# INNER CARTON

PUT TWO 12# INNER CARTON INTO 12# CARTON

12# CARTON

Packing belt

rohs Label

RoHS

Shipping marks according to customer's requirements

Epaper Identification
Model No.
Quantity:_____ pcs
Date: _____
Carton No. _____ of _____
Note:_____

14. Matched Development Kit

Our Development Kit designed for SPI E-paper Display aims to help users to learn how to use E-paper Display more easily. It can refresh black-white E-paper Display, three-color (black, white and red/Yellow) E-paper Display and four-color(black, white, red and yellow) Good Display 's E-pa per Display. And it is also added the functions of USB serial port, FLASH c hip, font chip, current detection ect.
Development Kit consists of the development board and the pinboard.

Supported development platforms include STM32, ESP32, ESP8266, Arduino UNO, etc. More details, please click to the following links:

STM32　　　　　　　https://www.good-display.com/product/219.html

ESP32　　　　　　　https://www.good-display.com/product/338.html

ESP8266　　　　　　https://www.good-display.com/product/220.html

Arduino UNO　　　　 https://www.good-display.com/product/222.html

15. Handling, Safety and Environmental Requirements

WARNING
The display glass may break when it is dropped or bumped on a hard surface. Handle with care. Should the display break, do not touch the electrophoretic material. In case of contact with electrophoretic material, wash with water and soap.

CAUTION
The display module should not be exposed to harmful gases, such as acid and alkali gases, which corrode electronic components.
Disassembling the display module can cause permanent damage and invalidate the warranty agreements.

Observe general precautions that are common to handling delicate electronic components. The glass can break and front surfaces can easily be damaged. Moreover the display is sensitive to static electricity and other rough environmental conditions.

Data sheet status	
Product specification	The data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and dose not form part of the specification.	

Product Environmental certification
RoHS

16. Precautions

(1) Do not apply pressure to the EPD panel in order to prevent damaging it.

(2) Do not connect or disconnect the interface connector while the EPD panel is in operation.

(3) Do not touch IC bonding area. It may scratch TFT lead or damage IC function.

(4) Please be mindful of moisture to avoid its penetration into the EPD panel, which may cause damage during operation.

(5) If the EPD Panel / Module is not refreshed every 24 hours, a phenomena known as "Ghosting" or "Image Sticking" may occur. It is recommended to refreshed the ESL / EPD Tag every 24 hours in use case. It is recommended that customer ships or stores the ESL / EPD Tag with a completely white image to avoid this issue

(6) High temperature, high humidity, sunlight or fluorescent light may degrade the EPD panel's performance. Please do not expose the unprotected EPD panel to high temperature, high humidity, sunlight, or fluorescent for long periods of time.